

PMV27UPEAR-VB Datasheet

-20V Trench SOT23-3 Single-P MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	- 20			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.034			
$R_{DS(on)}$ (Ω) at $V_{GS} = -2.5 \text{ V}$	0.046			
$R_{DS(on)}$ (Ω) at $V_{GS} = -1.8 \text{ V}$	0.067			
I _D (A)	- 5			
Configuration	Single			

FEATURES

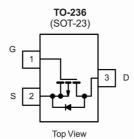
- · Halogen-free Option Available
- TrenchFET® Power MOSFET

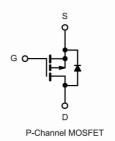


ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

· Load Switch for Portable Devices





ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unles	s otherwise noted)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	- 20	V
Gate-Source Voltage		V _{GS}	± 8	V
Continuous Drain Current	T _C = 25 °C	ī	- 5	
	T _C = 125 °C	- I _D	- 3	
Continuous Source Current (Diode Conduction)		Is	- 2.5	А
Pulsed Drain Current ^a		I _{DM}	- 20	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 11	
Single Pulse Avalanche Energy	L = 0.1 MH	E _{AS}	6	mJ
Maximum Power Dissipation ^a	T _C = 25 °C	D	2	W
	T _C = 125 °C	P_{D}	0.67	"
Operating Junction and Storage Temperatur	re Range	T _J , T _{stq}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^b	R _{thJA}	175	°C/W
Junction-to-Foot (Drain)		R _{thJF}	75	G/VV

TEL: 400-655-8788



PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	1						·
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 20	-	-	.,
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = - 250 μA	- 0.45	-	- 1	1 V
Gate-Source Leakage	I _{GSS}	V _{DS} =	= 0 V, V _{GS} = ± 8 V	-	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = - 12 V	-	-	- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = - 12 V, T _J = 125 °C	-	-	- 50	V nA μA
		V _{GS} = 0 V	V _{DS} = - 12 V, T _J = 175 °C	=	-	- 150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 4.5 V	V _{DS} ≤ - 5 V	- 10	-	-	Α
		V _{GS} = - 4.5 V	I _D = - 3.5 A	н	0.034	-	
		V _{GS} = - 4.5 V	I _D = - 3.5 A, T _J = 125 °C	-	0.066	-	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V	I _D = - 3.5 A, T _J = 175 °C	-	0.075	-	Ω
		V _{GS} = - 2.5 V	I _D = - 3 A	-	0.046	-	V nA μA A Ω S pF nC
		V _{GS} = - 1.8 V	I _D = - 2 A	-	0.067	-	
Forward Transconductanceb	9 _{fs}	V _{DS} =	- 5 V, I _D = - 1.6 A	-	7	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	695	870	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = - 6 V, f = 1 MHz	-	265	335	pF
Reverse Transfer Capacitance	C _{rss}			-	190	240	
Total Gate Charge ^c	Qg			-	8.4	13	
Gate-Source Charge ^c	Q _{gs}	$V_{GS} = -4.5 \text{ V}$	$V_{DS} = -6 \text{ V}, I_{D} = -3.85 \text{ A}$	-	1	-	nC
Gate-Drain Charge ^c	Q _{gd}			1	2.4	1	
Gate Resistance	Rg		f = 1 MHz	4.1	8.2	12.3	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	17	26	
Rise Time ^c	t _r		$=$ - 6 V, R _L = 1.6 Ω	-	19	29	ne
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D} \cong -3.85 \text{ A},$	V_{GEN} = - 4.5 V, R_g = 1 Ω	-	28	42] 115
Fall Time ^c	t _f			-	13	20	
Source-Drain Diode Ratings and Chara	acteristics ^b						
Pulsed Current ^a	I _{SM}			-	-	- 20	А
Forward Voltage	V _{SD}	I _F =	- 2 A, V _{GS} = 0 V	-	- 0.8	- 1.2	٧

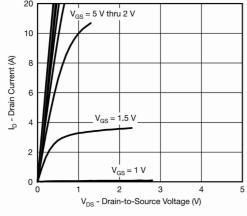
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

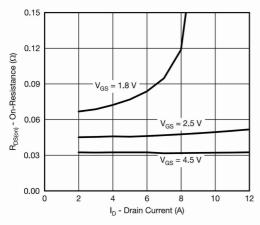
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



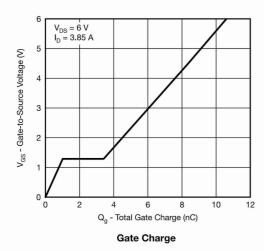
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

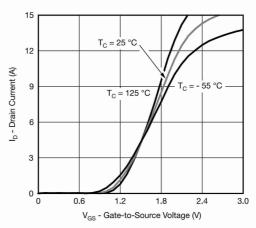


Output Characteristics

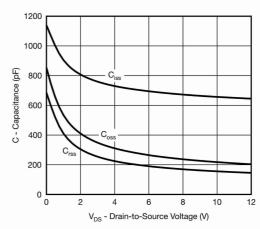


On-Resistance vs. Drain Current

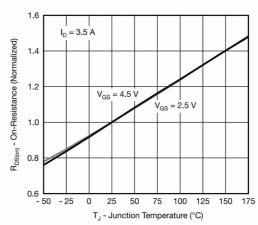




Transfer Characteristics



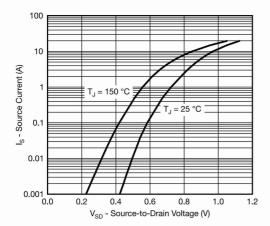
Capacitance



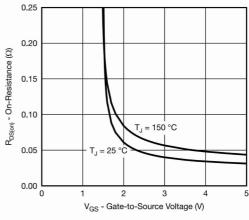
On-Resistance vs. Junction Temperature



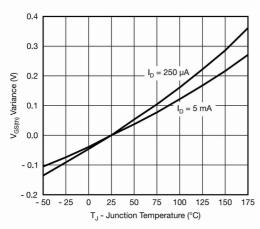
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



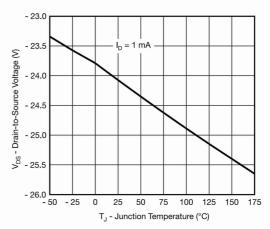




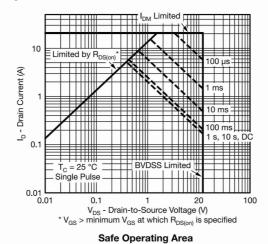
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

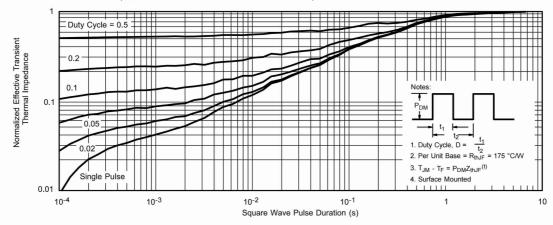


Drain Source Breakdown vs. Junction Temperature

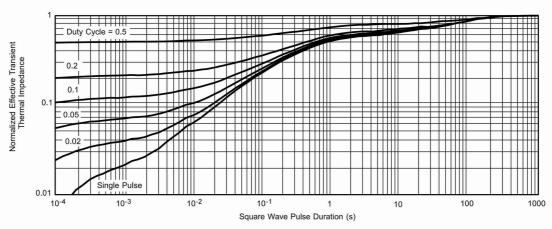




THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot



Normalized Thermal Transient Impedance, Junction-to-Ambient

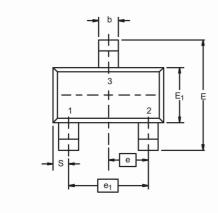
Note

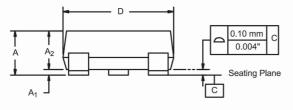
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

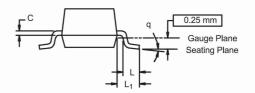
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOT-23 (TO-236): 3-LEAD





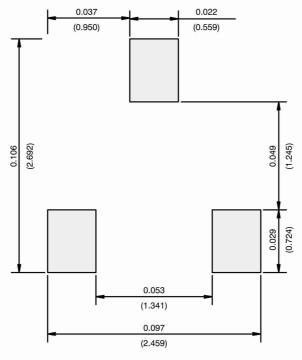


Dim	MILLIN	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025	Ref	
S	0.50 Ref		0.020	Ref	
q	3°	8°	3°	8°	

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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